

INTERNATIONAL STANDARD

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Mechanical standardization of semiconductor devices –

Part 6-4: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Measuring methods for package dimensions of ball grid array (BGA)

*Normalisation mécanique des dispositifs
à semiconducteurs –*

*Partie 6-4:
Règles générales pour la préparation des dessins
d'encombrement des dispositifs à semiconducteurs
à montage en surface –
Méthodes de mesure pour les dimensions des boîtiers
matriciels à billes*

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CONTENTS

FOREWORD	3
1 Scope	4
2 Normative references.....	4
3 Terms and definitions.....	4
4 Reference character and drawings.....	5
4.1 Ball grid array package (BGA) Type 1 – Ball datum	5
4.2 Ball grid array package (BGA) Type 2 – Body datum	6
Measuring method.....	7
5.1 Datum S as pertaining to ball coplanarity.....	7
5.2 Datum A, B	7
5.3 Definition of specified dimensions and measuring method	9
5.4 Profile of a package edge surface v.....	11
5.5 Mounting height A.....	12
5.6 First stand-off A1	12
5.7 Second stand-off A4	13
5.8 Ball diameter b	14
5.9 Ball centre position X.....	14
5.10 Ball coplanarity y	16
5.11 Package top flatness y1.....	16
Figure 1 – BGA package Type 1 – Ball datum	5
Figure 2 – BGA package Type 2 – Body datum	6
Figure 3 – Datum S	7
Figure 4 – Datum A, B – Type 1	8
Figure 5 – Centre of ball centres (for an even number).....	8
Figure 6 – Centre of ball centres (for an odd number)	8
Figure 7 – Datum A – Type 2.....	9
Figure 8 – Datum B – Type 2.....	9
Figure 9 – Tolerance w.....	10
Figure 10 – Measuring method of tolerance w	10
Figure 11 – Profile of a package edge surface v.....	11
Figure 12 – Measuring method of package edge surface v	11
Figure 13 – Mounting height A	12
Figure 14 – First stand-off A1	12
Figure 15 – Measuring method of stand-off A1	13
Figure 16 – Second stand-off A4	13
Figure 17 – Measuring method of stand-off A4	14
Figure 18 – Ball diameter b	14
Figure 19 – Ball centre position X	15
Figure 20 – Theoretically correct ball centre.....	15
Figure 21 – Measuring method of ball centre position X	15
Figure 22 – Ball coplanarity y	16
Figure 23 – Package top flatness y1.....	16

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**MECHANICAL STANDARDIZATION
OF SEMICONDUCTOR DEVICES –**

**Part 6-4: General rules for the preparation of outline drawings
of surface mounted semiconductor device packages –
Measuring methods for package dimensions of ball grid array (BGA)**

FOREWORD

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International Standard IEC 60191-6-4 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/531/FDIS	47D/546/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until 2006. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-4: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Measuring methods for package dimensions of ball grid array (BGA)

1 Scope

This part of IEC 60191 covers the requirements for the measuring methods of ball grid array (BGA) dimensions.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-6:1990, *Mechanical standardization of semiconductor devices – Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages*